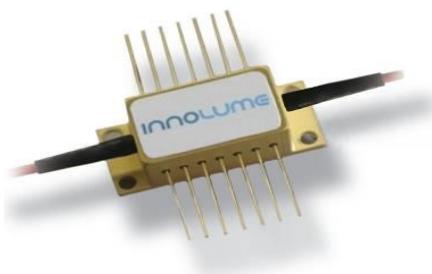


SOA-1140-90-YY-24dB Broad-band Semiconductor Optical Amplifier	
	<p>Features:</p> <ul style="list-style-type: none"> • Broad band (1100-1200nm) gain up to 24dB • Ultra low ripples 0.01dB (RMS) • Based on InAs/GaAs quantum dot chip • Strong linear polarization • RoHS compliance <p>Applications:</p> <ul style="list-style-type: none"> • Swept-source, tunable lasers • Booster optical amplifiers • Optical preamplifiers

SPECIFICATIONS				
Test conditions: CW operation, chip temperature 25°C, the case is mounted on room temperature heatsink				
Parameters	Min.	Typ.	Max.	Unit
Operating current (lop)		400	500	mA
Forward voltage @ lop		1.3	1.5	V
Gain				
Small signal gain ¹ ²	20	24		dB
Gain mean wavelength ¹	1125	1140	1155	nm
Gain bandwidth ¹ @ -3dB	70	90		nm
Amplitude of gain spectrum dip ¹		5	7	dB
Gain saturation output power ² @ -3dB	14	17		dBm
Noise figure ³ ***		4.5		dB
Amplified Spontaneous Emission (ASE)*				
ASE optical power ex fiber from each port	0.7	1		mW
ASE mean wavelength	1125	1140	1155	nm
ASE bandwidth @ -3dB		80		nm
Amplitude of ASE spectrum dip		5	7	dB
ASE ground state maximum position	1155	1170	1185	nm
ASE excited state maximum position	1095	1110	1125	nm
ASE** spectrum ripples ³ (RMS in 1nm range, 10pm resolution)		0.01	0.3	dB
ASE rise time		0.5		ns
ASE fall time		0.5		ns
ASE polarization extinction ratio (PER) at each port	15	18		dB

¹ at -25dBm input optical power

* without input light

² at wavelength of gain maximum

** from output port

³ at wavelength of ASE maximum

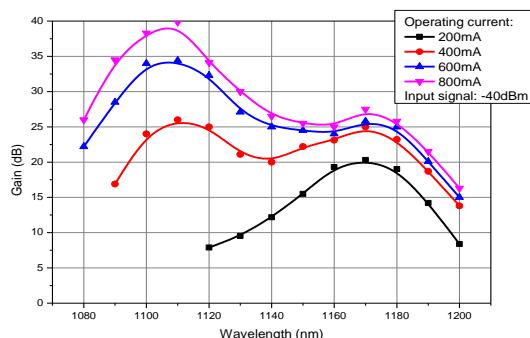
*** NF=10log₁₀(2p_{ASE}/Ghv) [D.Baney et al., Optical Fiber Techn. 6, 122 (2000)]

ABSOLUTE MAXIMUM RATINGS				
Parameters	Min.	Max.	Unit	
SOA reverse voltage	-	2	V	
SOA CW forward current	-	1000	mA	
Input optical power	-	20	dBm	
Thermo Electric Cooler current	-	3	A	
Thermo Electric Cooler voltage	-	4	V	
Fiber bend radius	3	-	cm	
Chip operating temperature range	10	40	°C	
Case operating temperature range	0	70	°C	
Storage temperature range	-40	85	°C	

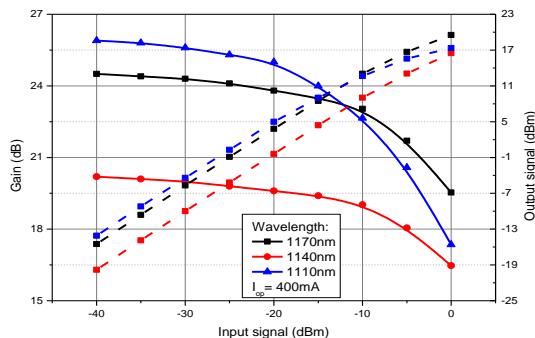
TYPICAL PERFORMANCE for reference only

Test conditions: CW operation, chip temperature 25°C, the case is mounted on room temperature heatsink

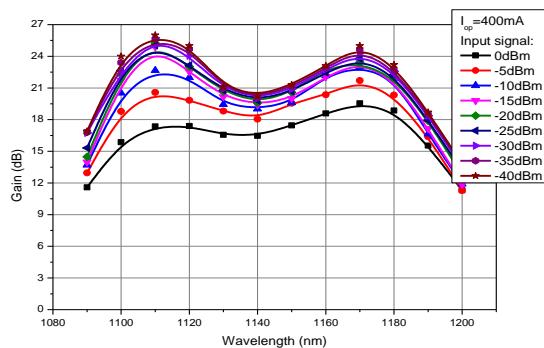
Gain spectra at different currents



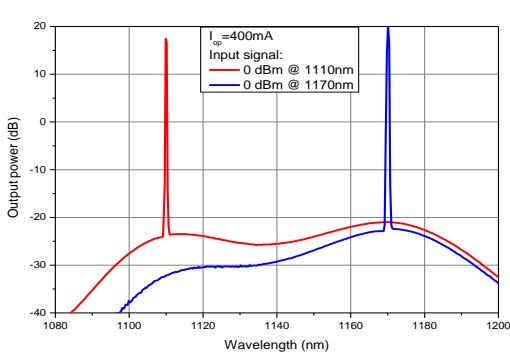
Gain and Output power vs. input signal



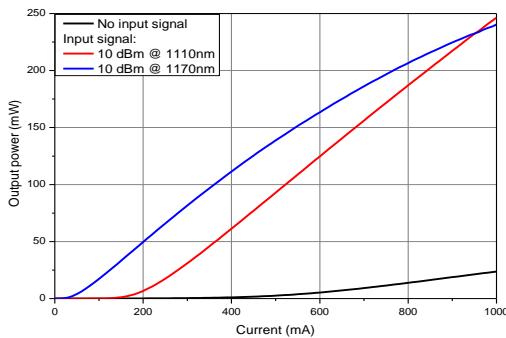
Gain spectra at different input signals



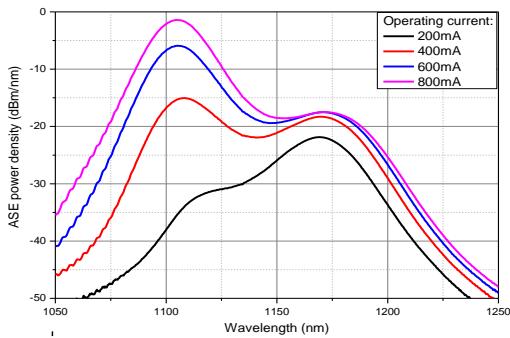
Spectra of amplified optical signal



Output power at different input signals



ASE Spectra (no input signal)



Part Number Identification

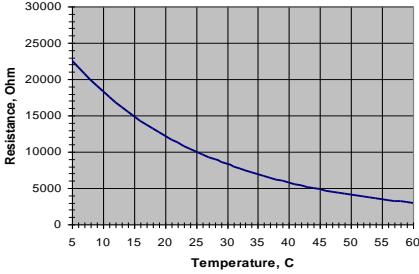
YY: Optical fiber type

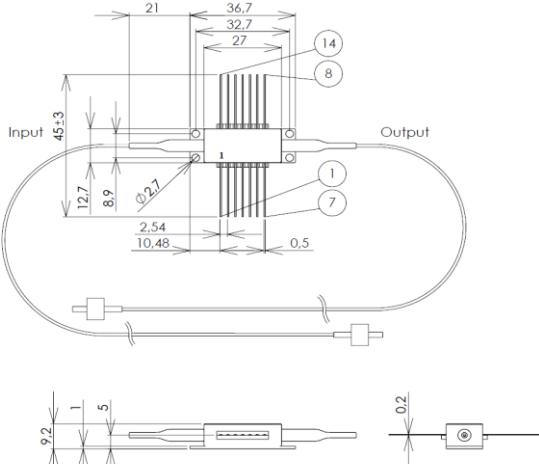
PM – PM980 fiber

HI – HI1060 fiber

Example: SOA-1140-90-PM-24dB

NOTE: Innolume product specifications are subject to change without notice

THERMISTOR SPECIFICATION			FIBER SPECIFICATION				
Parameters	Value	Unit	Parameters	HI1060	PM980		
Thermistor type	NTC	-	Numerical aperture (Typical)	0.14	0.12		
Resistance @25°C	10 ± 0.1	kOhm	Cutoff wavelength	920±50	900±70		
Beta 0-50°C	3375±1%	K	Mode-field diameter @1060nm	6.2±0.3	6.6±0.3		
R-T CURVE			Cladding diameter	125±1	125±1		
			Coating diameter	245±15	245±15		
			Length (each port)	1.0 ± 0.1	1.0 ± 0.1		
			Connector	FC/APC (narrow key)			
Connector alignment to the PANDA fiber							

DIMENSIONS (in mm)		Pin identification:
		1 TEC "+" 2 Thermistor 3 - 4 - 5 Thermistor 6 - 7 - 8 - 9 - 10 SOA anode "+" 11 SOA cathode "-" 12 - 13 Case 14 TEC "-"

SAFETY AND OPERATING INSTRUCTIONS

The light emitted from this device is invisible and can be harmful to the human eye. Avoid looking directly into the fiber connector when the device is in operation. Proper laser safety eyewear must be worn during operation with open connector. Absolute Maximum Ratings may be applied to the device for short period of time only. Exposure to maximum ratings for extended period of time or exposure to more than one maximum rating may cause damage or affect the reliability of the device. Operating the device outside of its maximum ratings may cause device failure or a safety hazard. Power supplies used with the component must be employed such that the maximum forward current cannot be exceeded.

A proper heatsink for the device on thermal radiator is required. The device must be mounted on radiator with 4 screws (bolt down in X-style fashion with initial torque set to 0.075Nm and final X-style bolt down at 0.15Nm) or with clamps. The deviation from flatness of radiator surface must be less than 0.05mm. It's recommended using of Indium foil or thermal conductive and soft material between bottom of the case and heatsink for thermal interface. It's undesirable to use thermal grease for this.

Avoid back reflection to the device. It may give impact on the device performance in aspects of spectrum and power stability. It also may cause fatal facet damage. Using of optical isolators is highly recommended to block back reflection.

Do not pull the fiber. Do not bend a fiber with a radius smaller than 3 cm. Fiber tip should always be protected from any contamination or damage during the process of installation. After removing the dust-preventing cap covered at fiber tip, carefully clean fiber tip by wiping through one direction using optical lens cleaning paper or cotton swab dabbed with Iso-Propanol or Ethyl alcohol. Operate the device with clean fiber connector only.

Electrostatic discharge is the primary cause of unexpected product failure. Take extreme precaution to prevent ESD. During device installation, ESD protection has to be maintained - use wrist straps, grounded work surfaces and rigorous antistatic techniques when handling the product.

